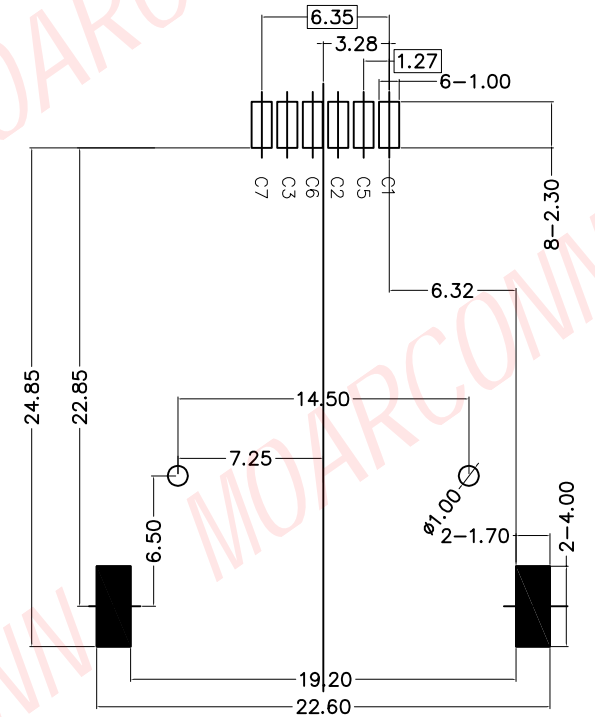
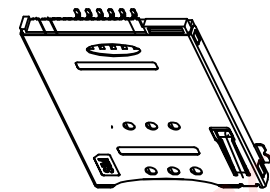
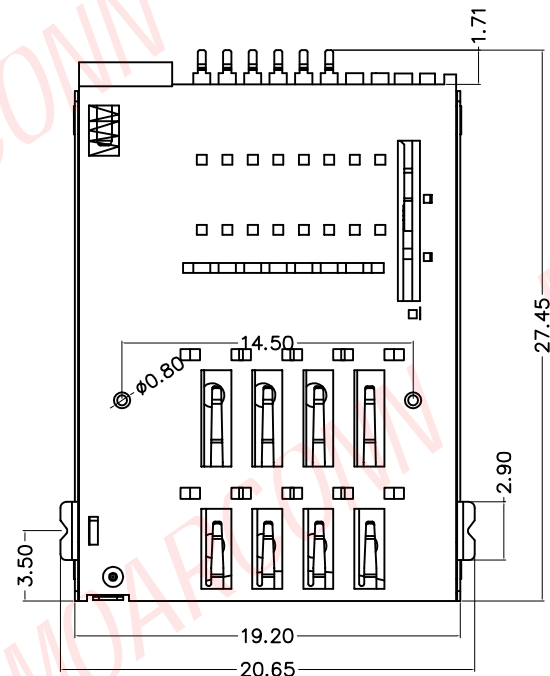
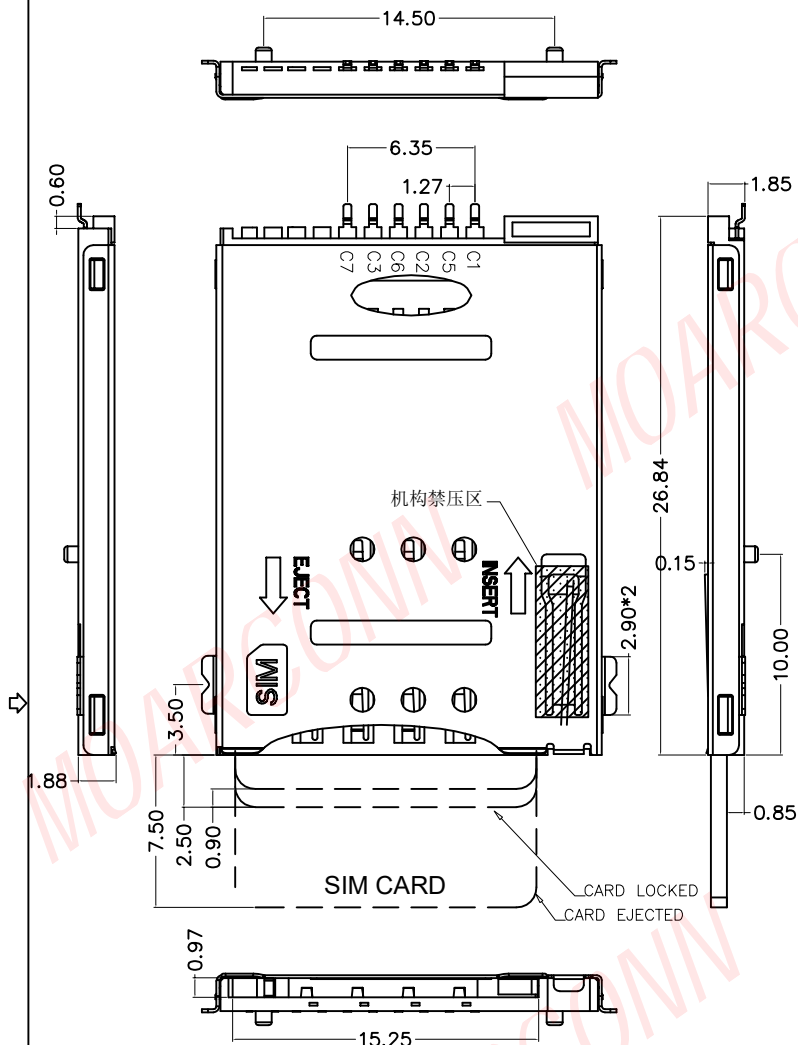


All materials, plating and process meet HF requirements.



RECOMMENDED PCB LAYOUT

1. SPECIFICATIONS
 INSULATION RESISTANCE: 500M min. AT DC 500V DC
 WITHSTANDING VOLTAGE: 250V ACrms FOR 1 MINUTE
 CONTACT RESISTANCE: 100M max. AT 10MA/20mV max
 CURRENT RATING: 0.5A
 VOLTAGE RATING: 5.0 vrms
 OPERATING TEMP. RANGE: -55 C+85 C
 MATING CYCLES: 5000 INSERTIONS

2. MATERIAL:
 INSULATOR: H-TEMPERATURE PLASTIC, UL 94V-0,
 COLOR: BLACK
 TERMINAL: COPPER ALLOY, T=0.15mm
 SHELL: STAINLESS STEEL, T=0.15mm

3. FINISH:
 TERMINAL: 50u" min NICKEL UNDERPLATED ON ALLOVER, GOLD PLATING
 ON CONTACT AREA, 80u" min TIN ON SOLDER TAIL.
 SHELL: 50u" NICKEL UNDERPLATED ON ALLOVER, GOLD FLASH ON SOLDER
 LATCH

SIM pin assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved



DONG GUAN MOARCONN ELECTRONIC Co., Ltd.

DIMENSIONS INIT:	mm
UNLESS OTHERWISE SPECIFIABLE	
DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.20
X.XXX: ±	0.10
ANGULAR: ±	2'

PRODUCT NAME :	SIM CARD CONN. PUSH TYPE 6PIN		DRAWING:	Faji	DATE:	2018.11.22	
PRODUCT NO. :	SM185-T1131-32-W		CHECK:		DATE:		
DRAWING NO. :	D-SM185-T1131-32-W		APPROVED:		DATE:		
SCALE:	1:1	DWG ID:	C D	REV.:	A	PAGE:	1 OF 1

A	---	Initial	Faji	2018.11.22
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				
2				
3				